



EtraLED-LUM-11020 LumiLEDs Modular Passive Star Heat Sink Φ110mm

Features VS Benefits

- * The EtraLED-LUM-11020 LumiLEDs Pin Fin LED Heat Sinks are specifically designed for luminaires using the LumiLEDs LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 1600 to 4,200 lumen.
- * Thermal resistance range Rth 1.79°C/W.
- * Modular design with mounting holes foreseen for direct mounting of LumiLEDs COB series.
- * Diameter 110.0mm standard height 20.0mm, Other heights on request.
- * Forged from highly conductive aluminum.

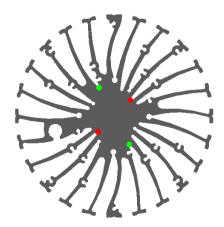
Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of LumiLEDs COB's and LED modules which standard fit on the srar LED heat sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of srar LED heat sinks.









LumiLEDs LED Modules directly Mounting Options LumiLEDs COB series.

LUXEON CoB 1202s: L2C5-xxxx1202E0600; LUXEON CoB 1202HD: L2C5-xxxx1202EH600;

With the Zhaga Book 11 holders for the red indicator marks.

TE Connectivity Holder: 2213118-2;

Without the holders for the blue indicator marks. Direct mounting with machine screws M3x6.5mm.

LUXEON CoB 1202: L2C5-xxxx1202E0900;

With the Zhaga Book 3 holders for the green indicator marks. TE Connectivity Holder: 2213382-1; Without the holders for the pink indicator marks. Direct mounting with machine screws M3x6.5mm.

LuXEon CX Plus CoB series.

With the Zhaga Book 11 holders for the red indicator marks.

BJB Holder:47.319.6104.50; Direct mounting with machine screws M3x6.5mm.





EtraLED

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Mounting Options and Drawings & Dimensions

Example: EtraLED-LUM-11020-B-1,2

Example: EtraLED-LUM-110 1 - 2 -



Height (mm)



B-Black

C-Clear Z-Custom

Mounting Options - see graphics for details Combinations available

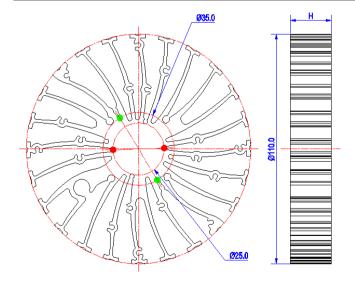
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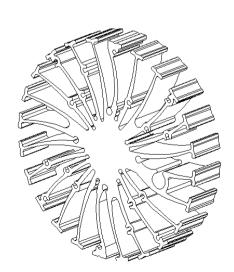
means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

MOUNTING OPTION	Module type	Holder NO.	LEDiL products		THREAD	THREAD	THREAD HOLE
			Ronda series	Olivia series	INCEAD	DEPTH	DISTANCE
1	LUXEON CoB M02; LUXEON CoB M03;	BJB Holder 47.319.6104.50	FN15xxx-xx;	1	МЗ	6.5mm	25.0mm/ 2-@180°
	LUXEON 1202s; LUXEON 1202HD;	BJB Holder 47.319.6180.50					
		TE Holder 2213118-2					
2	LUXEON 1202; LUXEON 1203;	TE Holder 2213382-1			М3	6.5mm	35.0mm/ 2-@180° (Zhaga Book 3)



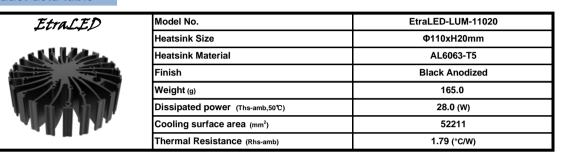








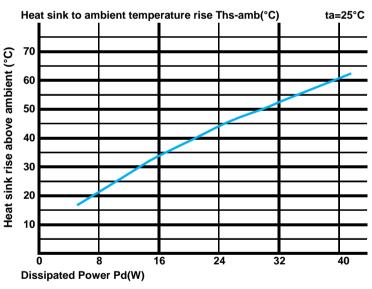
The product deta table



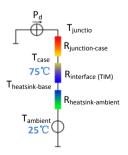
The thermal data table

- * Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- *To calculate the dissipated power please use the following formula: $Pd = Pe \times (I \eta L)$.
 - Pd Dissipated power ; Pe Electrical power ; $\eta L =$ Light effciency of the LED module;

Pd = Pe x (1-ηL)		Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)		
		EtraLED-LUM-11020			
Dissipated Power Pd(W)	8.0	2.50	20.0		
	16.0	2.06	33.0		
	24.0	1.83	44.0		
	32.0	1.63	52.0		
	40.0	1.50	60.0		



- *The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- $\label{thm:module} \mbox{MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.}$
- $Either thermal\ grease, A\ thermal\ pad\ or\ a\ phase\ change\ thermal\ pad\ thickness\ 0.1-0.15 mm\ is\ recommended.$



- *Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths Ta)/Pd$
- θ Thermal Resistance [°C/M]; Ths Heatsink temperature; Ta Ambient temperature;
- *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface}(TIM)$ ["C,M"], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ ["C,M"], and the ambient temperature is $T_{ambient}$ ["C].
- *Thermal resistances outside the package $R_{interface \, (TIM)}$ and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used: $T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$

Tel:+86-769-39023131
Fax:+86-(020)28819702 ext:22122
Email:sales@mingfatech.com
Http://www.heatsinkled.com
Http://www.mingfatech.com

